L Number	Hits	Search Text	DB	Time stamp
1	159	((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/28 14:19
2	12	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/28 14:20
-	1400	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:13
-	575	257/688	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:13
-	243	257/689	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:13
-	655	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:15
-	480	257/785	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:15
-	2708	257/686 257/688 257/689 257/685 257/785	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:15
-	185	(257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:54
-	23	5043794.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:40
-	35	5434745.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:44
-	69	5128831.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 07:51
-	69	5128831.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:00
-	4	"5872025"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:00
-	2	"6180881"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:00
-	18	"5579207"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:00
-	24	"5872025" "6180881" "5579207"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:26

–	16	5579207.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:12
–	16025	((stacked stack) with (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:47
–	356	(((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:48
–	289	((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:38
–	289	(((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:38
–	107	((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) and (ground grounded grounding)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:54
–	182	((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) not ((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) and (ground grounded grounding))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:22
–	68	(((stacked stack) with (chip semiconductor))) and (vertical$2 near1 connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:44
–	91	(((stacked stack) with (chip semiconductor))) and (vertical$2 near1 (mounting connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:51
–	32	5371654.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:54
–	2314	257/686 257/688 257/689 257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:51
–	325	(257/686 257/688 257/689 257/685) and spring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:52

–	6	(257/686 257/688 257/689 257/685) and (spring near1 terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:53
–	1	6147411.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:55
–	2	6089920.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:00
–	1	6147411.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:01
–	8	(((stacked stack) with (chip semiconductor))) and (vertical$2 near1 surface near1 mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:19
–	85	(((stacked stack) with (chip semiconductor))) and ((spring clip) near1 (contact connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:39
–	85	((((stacked stack) with (chip semiconductor))) and ((spring clip) near1 (contact connection))) not ((((stacked stack) with (chip semiconductor))) and (vertical$2 near1 connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:21
–	2	5910885.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:26
–	112	(((stacked stack) with (chip semiconductor))) and (((spring clip) near1 (contact connection)) (clip near spring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:40
–	139	(((stacked stack) with (chip semiconductor))) and (((spring clip) near1 (contact connection)) (leaf near spring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:41
–	148	(((stacked stack) with (chip semiconductor))) and (((spring clip) near1 (contact connection)) (leaf near spring) (clip near1 lead))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:41
–	27	(((((stacked stack) with (chip semiconductor))) and (((spring clip) near1 (contact connection)) (clip near spring))) not ((((((stacked stack) with (chip semiconductor))) and ((spring clip) near1 (contact connection))) not ((((stacked stack) with (chip semiconductor))) and (vertical$2 near1 connection)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 13:41
–	54	(((((stacked stack) with (chip semiconductor))) and (((spring clip) near1 (contact connection)) (leaf near spring))) not ((((((stacked stack) with (chip semiconductor))) and ((spring clip) near1 (contact connection))) not ((((stacked stack) with (chip semiconductor))) and (vertical$2 near1 connection)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 14:10
–	18193	((stacked stack) with (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:14
–	445	(((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:53

–	17	((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) and (vertical$2 near1 (mounting connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:51
–	206	((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) and (bump ball bga flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:53
–	208	(257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:54
–	10172	((stacked stack) near3(chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:15
–	3259	(((stacked stack) near3(chip semiconductor))) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
–	2885	((((stacked stack) near3(chip semiconductor))) and lead) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
–	14814	((stacked stack) near3 (chip package semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
–	4189	(((stacked stack) near3 (chip package semiconductor))) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
–	3605	((((stacked stack) near3 (chip package semiconductor))) and lead and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:19
–	3278	(((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:20
–	233	((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:21
–	35	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))) and ((chip adj select) (clock adj enable))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:21
–	28	5455740.URPN.	USPAT	2003/03/23 14:34
–	1	6242285.URPN.	USPAT	2003/03/23 14:36

–		52	("Re36229" | "4956694" | "5138438" | "5221642" | "5236117" | "5279029" | "5313096" | "5332922" | "5367766" | "5369056" | "5369058" | "5371866" | "5377077" | "5420751" | "5446620" | "5448450" | "5455740" | "5479318" | "5484959" | "5493476" | "5498906" | "5499160" | "5512783" | "5528075" | "5543664" | "5550711" | "5552963" | "5561591" | "5566051" | "5572065" | "5581121" | "5585668" | "5586009" | "5588205" | "5592364" | "5605592" | "5612570" | "5615475" | "5631193" | "5654877" | "5702985" | "5778522" | "5783464" | "5801437" | "5804870" | "5811877" | "5828125" | "5843807" | "5864175" | "5869353" | "5895232" | "5945732").PN.	USPAT	2003/03/23 14:37
–		4	5778522.URPN.	USPAT	2003/03/23 14:39
–		16	("4103318" | "4932873" | "4956694" | "5057026" | "5236117" | "5279029" | "5279991" | "5281852" | "5367766" | "5394010" | "5475920" | "5499160" | "5514907" | "5523619" | "5543664" | "5592364").PN.	USPAT	2003/03/23 14:40
–		10	5811877.URPN.	USPAT	2003/03/23 14:46
–		6	("4620215" | "5068712" | "5157478" | "5299092" | "5394010" | "5554886").PN.	USPAT	2003/03/23 14:47
–		11	"5512783"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:06
–		25	"5760471"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:12
–		0	6262476.URPN.	USPAT	2003/03/23 16:16
–		7	("4696525" | "5138438" | "5323060" | "5479318" | "5508563" | "5530292" | "5760471").PN.	USPAT	2003/03/23 16:16
–		0	6213747.URPN.	USPAT	2003/03/23 16:18
–		30	("3404454" | "4682270" | "4778641" | "5095402" | "5172214" | "5200364" | "5214845" | "5331235" | "5418189" | "5436500" | "5466887" | "5471369" | "5475259" | "5483024" | "5486720" | "5493153" | "5498902" | "5508565" | "5519251" | "5527743" | "5530286" | "5530292" | "5535509" | "5554823" | "5554886" | "5570272" | "5572068" | "5679978" | "5760471" | "6007317").PN.	USPAT	2003/03/23 16:18
–		122	((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/28 14:19
–		8	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/28 14:20
–		114	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) not (((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:54

—	81	((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) not ((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3))) not ((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))) and ((chip adj select) (clock adj enable)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:54
—	8	5648681.URPN.	USPAT	2003/03/23 16:56
—	3	("5276352" | "5424576" | "5457341").PN.	USPAT	2003/03/23 16:56
—	5	"6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:59
—	47	(US-6297548-$ or US-5857858-$ or US-5600541-$ or US-5579207-$ or US-5434745-$ or US-5838060-$ or US-5995379-$ or US-6314013-$ or US-6255726-$ or US-6195268-$ or US-6180881-$ or US-5872025-$ or US-6147411-$ or US-5371654-$ or US-6210993-$ or US-5910010-$ or US-6472734-$ or US-6462408-$ or US-6252299-$ or US-5978227-$ or US-5811877-$ or US-5631193-$ or US-5605592-$ or US-5493476-$ or US-5484959-$ or US-5455740-$).did. or (US-6242285-$ or US-6404662-$ or US-5895232-$ or US-5801437-$ or US-5778522-$ or US-5592364-$ or US-5588205-$ or US-5543664-$ or US-5512783-$ or US-5138438-$ or US-6205654-$ or US-5394010-$ or US-6084293-$ or US-6028352-$ or US-6518659-$ or US-6459148-$ or US-6424031-$ or US-6399420-$ or US-6265660-$ or US-6262476-$ or US-5648681-$).did.	USPAT	2003/03/24 07:09
—	15	(chip adj select) with (connected connection connecting) with (clock adj enable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:17
—	0	(("not" no) near (connected connection)) with (connected connection connecting) with (clock adj enable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:22
—	9819	(("not" "no") adj (connected connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:21
—	0	((("not" "no") adj (connected connection))) with (connected connection connecting) with (clock adj enable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:22

–	47	(US-5371654-$ or US-5138438-$ or US-5394010-$ or US-6472734-$ or US-6518659-$ or US-6252299-$ or US-6462408-$ or US-6459148-$ or US-6424031-$ or US-6404662-$ or US-6265660-$ or US-6297548-$ or US-6399420-$ or US-6314013-$ or US-6262476-$ or US-6255726-$ or US-6242285-$ or US-6205654-$ or US-6210993-$ or US-6147411-$ or US-6084293-$ or US-6195268-$ or US-6180881-$ or US-5910010-$ or US-6028352-$ or US-5978227-$).did. or (US-5995379-$ or US-5872025-$ or US-5857858-$ or US-5895232-$ or US-5811877-$ or US-5838060-$ or US-5801437-$ or US-5778522-$ or US-5648681-$ or US-5631193-$ or US-5605592-$ or US-5588205-$ or US-5592364-$ or US-5600541-$ or US-5512783-$ or US-5579207-$ or US-5543664-$ or US-5493476-$ or US-5434745-$ or US-5455740-$ or US-5484959-$).did.	USPAT	2003/07/21 10:24
–	1	6472734.URPN.	USPAT	2003/07/21 10:25
–	3	("5490324" | "6291259" | "6172432").PN.	USPAT	2003/07/21 10:25
–	4	6297548.URPN.	USPAT	2003/07/21 10:27